13 JUN 2002
20020035269

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

162162

(43) International Publication Date
28 June 2001 (28.06.2001)

PCT

(10) International Publication Number
WO 01/46997 A1

(51) International Patent Classification[7]: H01L 21/00

(21) International Application Number: PCT/US00/34753

(22) International Filing Date:
19 December 2000 (19.12.2000)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
09/470,690 23 December 1999 (23.12.1999) US

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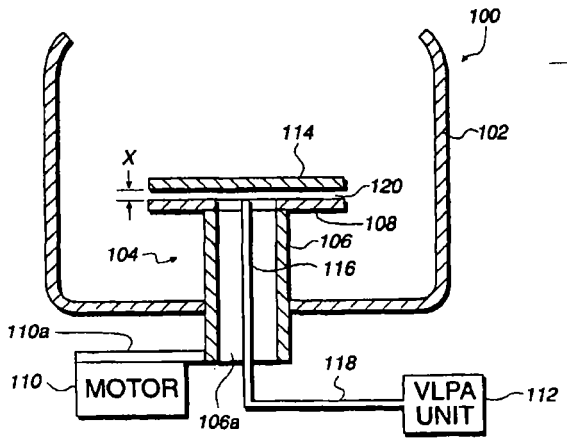
(81) Designated States *(national)*: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CR, CU, CZ, DE, DK, DM, DZ, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, TZ, UA, UG, US, UZ, VN, YU, ZA, ZW.

(84) Designated States *(regional)*: ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG).

Published:
— *With international search report.*
— *Before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments.*

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: HOLLOW CORE SPINDLE AND SPIN, RINSE, AND DRY MODULE INCLUDING THE SAME



ACTION

(57) Abstract: A spindle includes a hollow central shaft having an upper end and a lower end. The hollow central shaft defines a channel for transmitting fluid through the spindle. A wafer backing plate is disposed at the upper end of the hollow central shaft. The wafer backing plate reduces particle recontamination on the backside of a semiconductor wafer disposed above the spindle by preventing particles from contacting the backside of the wafer during spin processing. A spin, rinse, and dry module includes a bowl and a hollow cores spindle for rotating a wafer that extends into the bowl. The hollow core spindle has a channel defined therein for transmitting a fluid to the backside of the wafer and a wafer backing plate disposed at an upper end thereof for preventing particles from contacting the backside of the wafer during spin processing.

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